

2SJ605-Z-VB Datasheet

P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	ר) ו _D (A) ^a Q _g (Typ			
- 60	0.019 at V _{GS} = - 10 V	- 80	76 nC		
	0.025 at V _{GS} = - 4.5 V	- 70	70110		

FEATURES

- Trench Power MOSFET
- 100 % UIS Tested

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APPLICATIONS

Load Switch





Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 60	V
Gate-Source Voltage		V _{GS}	± 20	v
	T _C = 25 °C		- 80 ^a	
Continuous Drain Current (T = $150 ^{\circ}$ C)	T _C = 70 °C		- 70	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	9.2 ^b	A
	T _A = 70 °C		- 8.1 ^b	A
Pulsed Drain Current		I _{DM}	- 150	
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	- 45	
Single Pulse Avalanche Energy		E _{AS}	101	mJ
Continuous Source-Drain Diode Current	T _C = 25 °C		69 ^a	А
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.1 ^b	~
	T _C = 25 °C		104.2 ^a	
Maximum Power Dissipation	T _C = 70 °C	PD	66.7 ^a	w
	T _A = 25 °C	' D	3.1 ^b	vv
	T _A = 70 °C		2 ^b	
Operating Junction and Storage Temperature R	ange	T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	33	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.98	1.2	C/VV	

Notes:

a. Based on $T_C = 25 \ ^{\circ}C$.

b. Surface mounted on 1" x 1" FR4 board.

SPECIFICATIONS (T _J = 25 °C,	unless othe	erwise noted)					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = -250 \mu A$	- 60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		68		mV/°0	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = -250 \mu A$		- 5.2			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1		- 3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10	μA	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A		0.019		<u> </u>	
		V _{GS} = - 4.5 V, I _D = - 20 A		0.025		Ω	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 15 V, I _D = - 50 A	20			s	
Dynamic ^b					•	•	
Input Capacitance	C _{iss}			3500		pF	
Output Capacitance	C _{oss}	V _{DS} = - 25 V, V _{GS} = 0 V, f = 1 MHz		390			
Reverse Transfer Capacitance	C _{rss}			290			
	Qg	V_{DS} = - 30 V, V_{GS} = - 10 V, I_{D} = - 55 A		76		1	
Total Gate Charge				38		nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -30$ V, $V_{GS} = -4.5$ V, $I_{D} = -55$ A		16			
Gate-Drain Charge	Q _{gd}			19			
Gate Resistance	Rg	f = 1 MHz		5.2		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	tr	$V_{DD} = -2 V, R_L = 2 \Omega$		7	15	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		70	110		
Fall Time	t _f			40	60		
Drain-Source Body Diode Characteristic	s			•			
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 69	A	
Pulse Diode Forward Current ^a	I _{SM}			1	- 150		
Body Diode Voltage	V _{SD}	I _S = - 30 A		- 1	- 1.5	V	
Body Diode Reverse Recovery Time	t _{rr}			45	68	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			59	120	nC	
Reverse Recovery Fall Time	t _a	· I _F = - 50 A, di/dt = 100 A/μs, T _J = 25 °C		29		1	
Reverse Recovery Rise Time	t _b			16		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

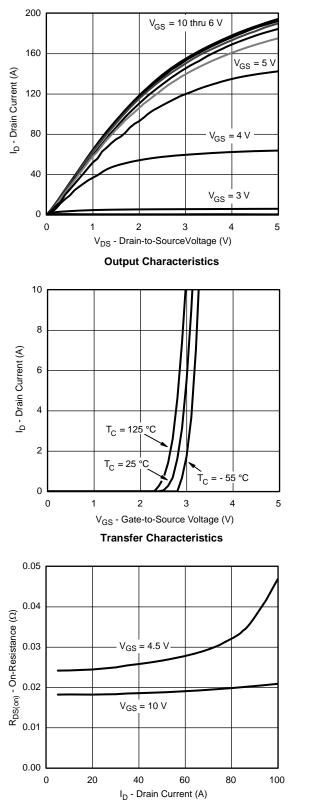
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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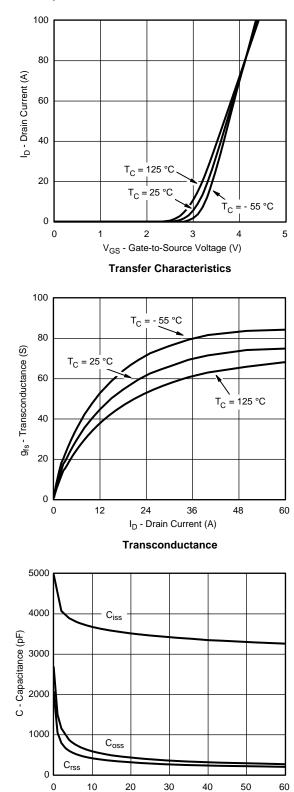
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

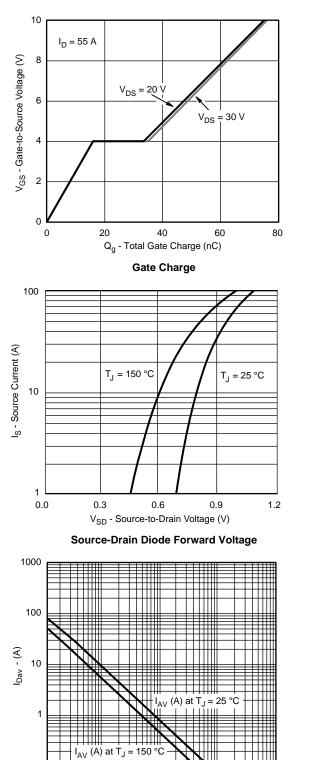
On-Resistance vs. Drain Current



V_{DS} - Drain-to-Source Voltage (V)

Capacitance





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

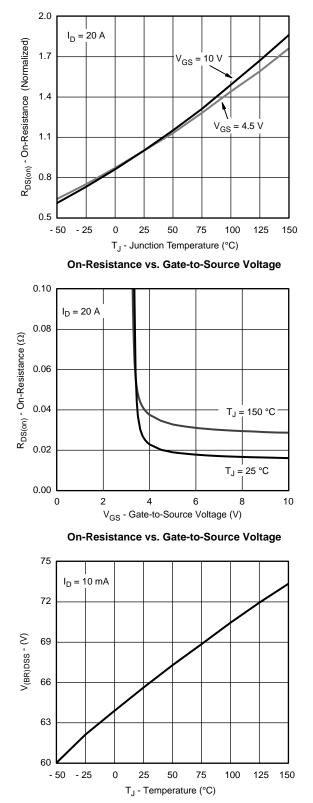
 $\label{eq:Tin-s} T_{in} \text{ - } (s)$ Single Pulse Avalanche Current Capability vs. Time

0.01

0.1

1

11111



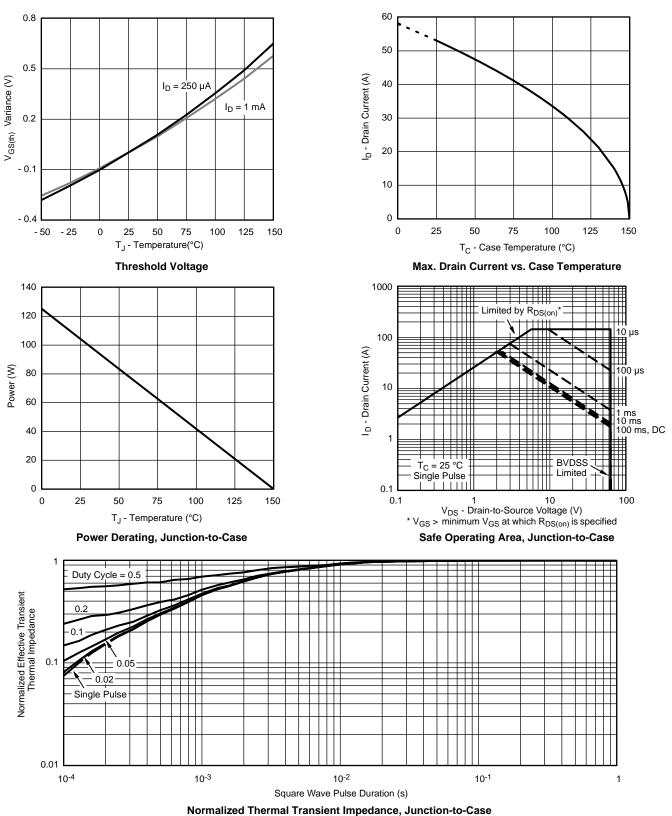
Drain-Source Breakdown Voltage vs. Junction Temperature

0.1

0.0001

0.001

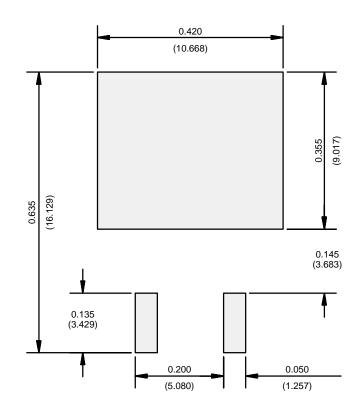




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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